

# **THERMAL DISSIPATION ASSEMBLY AND FABRICATION METHOD FOR ELECTRONICS DRAWER OF A MULTIPLE-DRAWER ELECTRONICS RACK**

## **Abstract of the Disclosure**

A thermal dissipation assembly and method, and a cooled multi-drawer electronics rack are provided having a first cooling loop and a second cooling loop. The first cooling loop is disposed substantially within an electronics drawer and positioned to extract heat from an electronics module within the drawer. The first cooling loop further includes a first planar heat transfer surface. The second cooling loop is disposed substantially external to the electronics drawer and includes a second planar heat transfer surface. A biasing mechanism mechanically forces the first planar heat transfer surface and the second heat transfer surface coplanar when the electronics drawer is in a docked position in the electronics rack to facilitate the transfer of heat from the first cooling loop to the second cooling loop.